



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

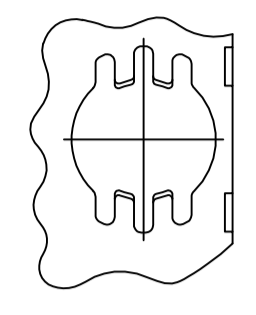
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

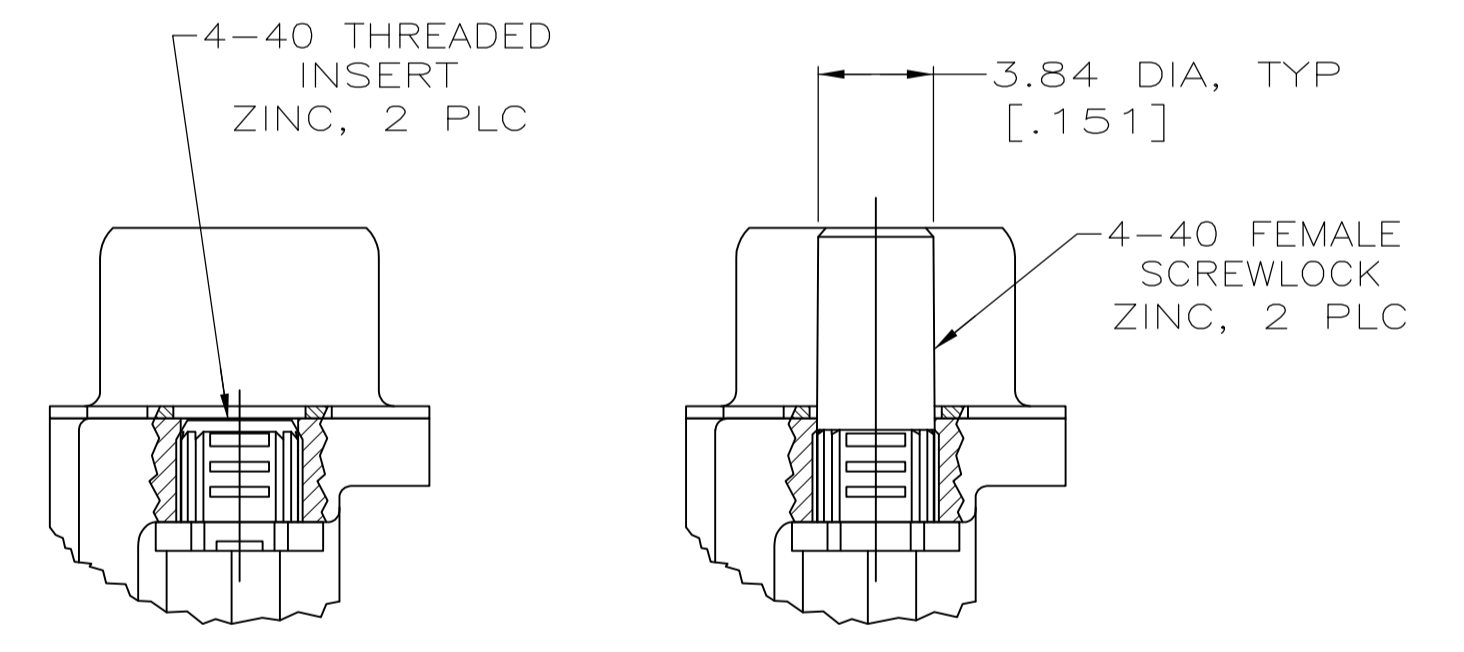
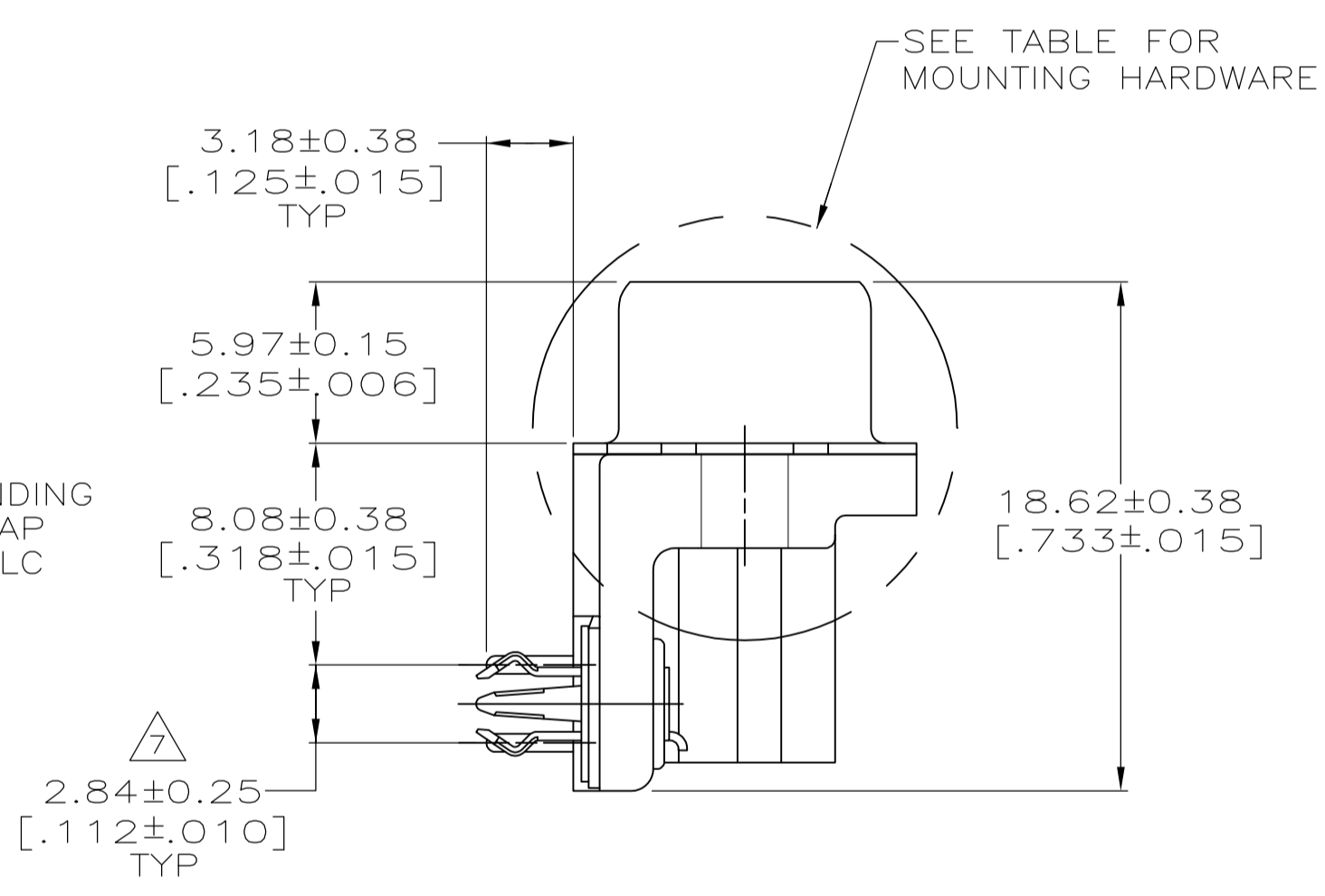
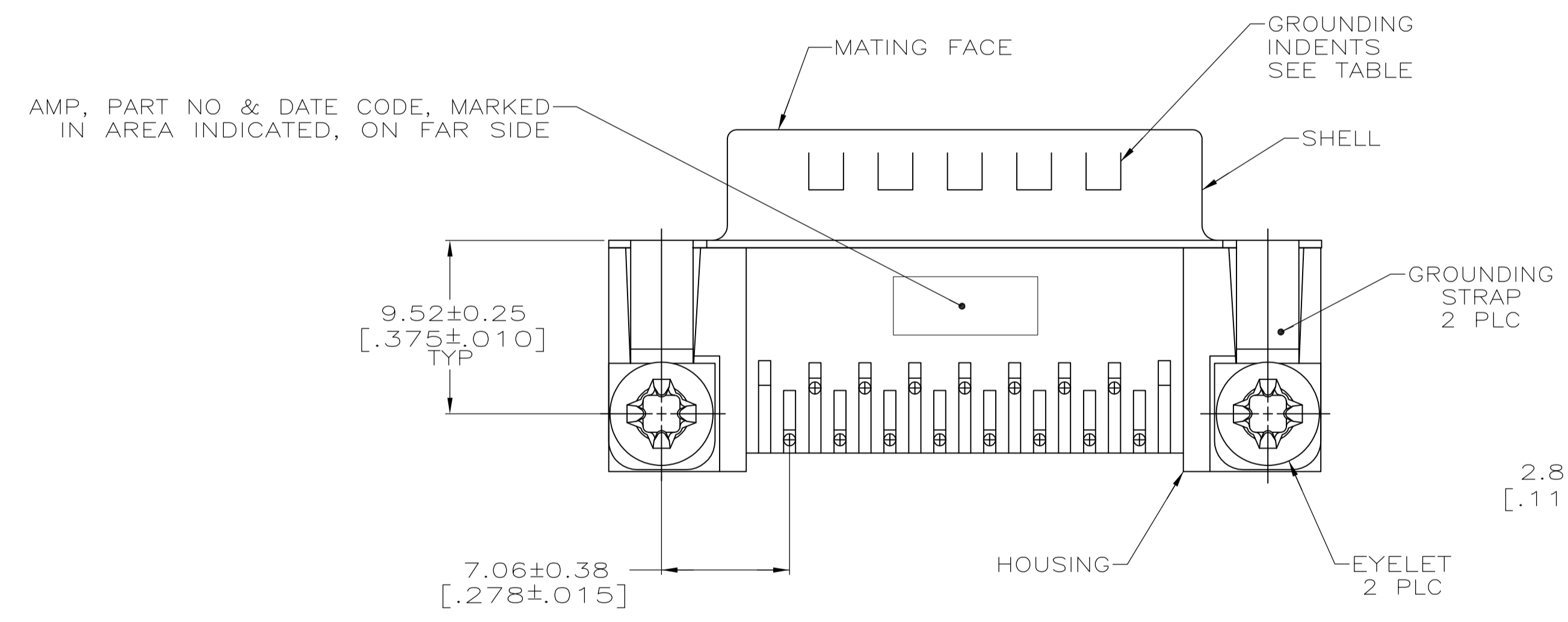
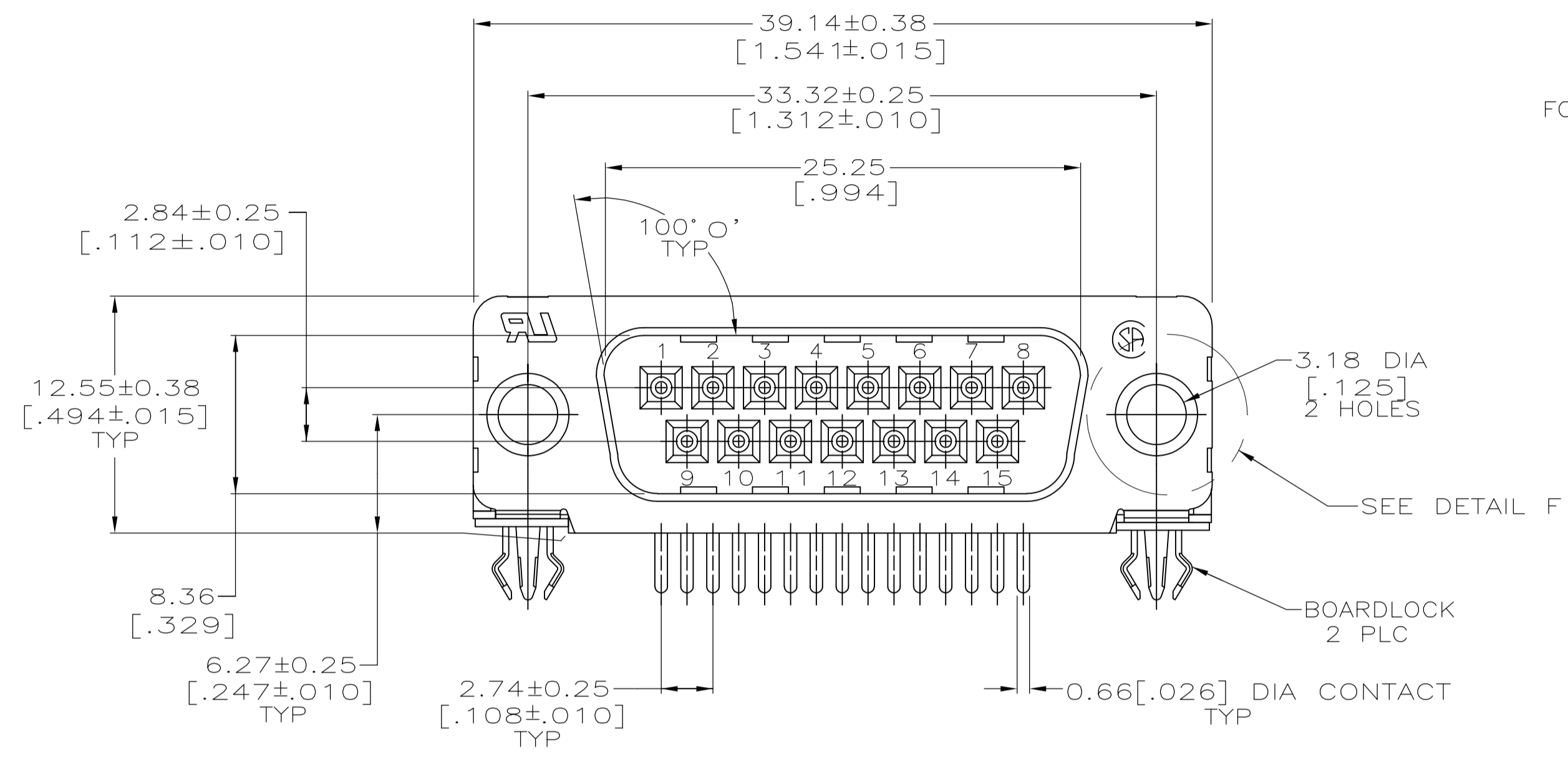


- △ HOUSING: NYLON OR POLYESTER, FLAME RETARDANT 94V-0 RATED, GLASS FILLED, BLACK
- SHELLS: CARBON STEEL
- CONTACTS: BRASS
- BOARDLOCKS: COPPER ALLOY
- EYELETS: BRASS
- △ SHELLS: 2.54μm [.000100] MIN TIN OVER 1.27μm [.000050] MIN COPPER.
- EYELETS: 5.08μm [.000200] MIN TIN OVER COPPER FLASH.
- CONTACTS AND BOARDLOCKS: SEE TABLE.
- INSERTS AND SCREWLOCKS: CLEAR CHROMATE.
- △ GOLD FLASH ON THE MATING SURFACES, 2.54μm [.000100] MIN TIN OR TIN-LEAD PLATE ON THE SOLDER END, 1.27μm [.000050] MIN NICKEL UNDERPLATE ON THE ENTIRE CONTACT.
- △ 0.76μm [.000030] MIN GOLD PLATE ON THE MATING SURFACES, 2.54μm [.000100] MIN TIN OR TIN-LEAD PLATE ON THE SOLDER END, 1.27μm [.000050] MIN NICKEL UNDERPLATE ON THE ENTIRE CONTACT
- OR-
- GOLD FLASH OVER PALLADIUM-NICKEL PLATE, 0.76μm [.000030] MIN TOTAL ON THE MATING SURFACES, 2.54μm [.000100] MIN TIN OR TIN-LEAD PLATE ON THE SOLDER END, 1.27μm [.000050] MIN NICKEL UNDERPLATE ON THE ENTIRE CONTACT.
- △ 5.08μm [.000200] MIN TIN-LEAD OVER 1.27μm [.000050] MIN NICKEL.
- △ 5.08μm [.000200] MIN TIN OVER 1.27μm [.000050] MIN NICKEL.
- △ DIMENSION APPLIES FROM CENTER OF CONTACTS.
- △ SUPERSEDED BY 747841-2.
- △ SUPERSEDED BY 747841-6.
- △ OBSOLETE.

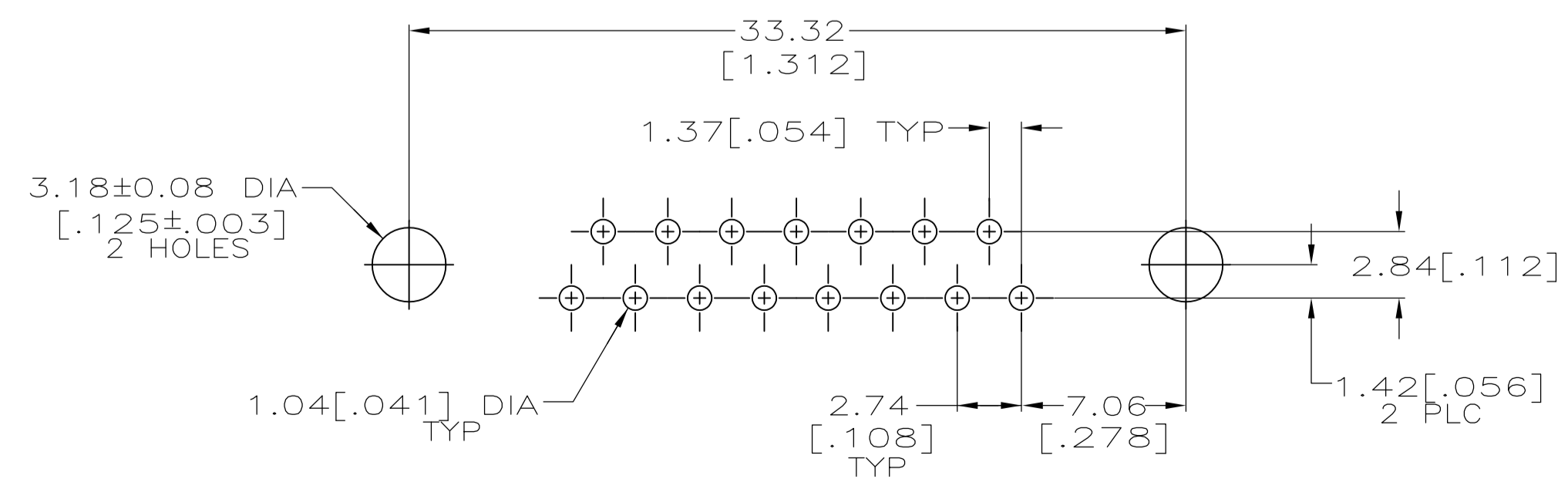


FOR -5 AND -6 ONLY

DETAIL F  
2 PLC



DETAIL D      DETAIL E



P.C. BOARD MOUNTING DIMENSIONS  
P.C. BOARD THICKNESS: 1.57[.062]

YES	SEE DETAIL E	△6	△4	6-747841-8
YES	SEE DETAIL D	△6	△4	6-747841-7
NO	-	△5	△4	△10 747841-7
YES	SEE DETAIL E	△5	△4	747841-6
YES	SEE DETAIL E	△5	△3	△9 747841-5
YES	SEE DETAIL D	△5	△4	747841-4
YES	SEE DETAIL D	△5	△3	△10 747841-3
YES	-	△5	△4	△10 747841-2
YES	-	△5	△3	△8 747841-1
GROUNDING INDENTS	MOUNTING HARDWARE	BOARDLOCK FINISH	CONTACT FINISH	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	APPROVED: M.D. GALLOWAY	DATE: 06 FEB 90
0 PLC ± -	1 PLC ± -	2 PLC ± -	3 PLC ± 0.13[.005]
4 PLC ± -	ANGLES ± 2°	APPLICATION SPEC: 108-40025	SIZE: 114-40010
MATERIAL: △	FINISH: △	WEIGHT: -	SCALE: 4:1

W.G. LENKER 05 OCT 89  
R. STONE 05 FEB 90  
M.D. GALLOWAY 06 FEB 90

**STE** TE Connectivity

PLUG ASSEMBLY, SIZE 2, 15 POSITION, RIGHT ANGLE, FRONT METAL SHELL, .318 SERIES, BOARDLOCKS, AMPLIMITE® HD-20

00779C=747841

CUSTOMER DRAWING      SHEET 1 OF 1      REV V